Appl. No. 10/707,824
Amdt. dated August 12, 2005
Reply to Office action of May 13, 2005

<u>**Listing of Claims:**</u>

1.   (original)A method of defect review comprising following steps:

providing a wafer with a plurality of defects;

performing a defect inspection to detect the defects;

5   performing an automatic defect classification according to a database to separate the defects into a plurality of defect types; and

performing a defect review;

wherein each defect type has different sampling ratios in the defect review according to its influence degree of process yield.

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2.   (original)The method of claim 1 wherein the database comprises information about the plurality of defect types and defect information corresponding to each defect type.

3.   (original)The method of claim 2 wherein the defect information comprises the

15   influence degree of the process yield of each defect type.

4.   (original)The method of claim 3 wherein the database separates the defect types into killer defects and non-killer defects according to the influence degree of the process yield.

20   5.   (original)The method of claim 4 wherein the sampling ratio of the killer defects in the defect review is larger than that of the non-killer defects.

6.   (original)The method of claim 3 wherein the database separates the defects into pre-layer defects and adding defects, and further separates the adding defects into killer

25   defects and non-killer defects.

7.   (original)The method of claim 6 wherein the defect review focuses on the adding

2

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defects.

8.   (original)The method of claim 1 wherein after finishing the defect inspection, a judgment of cluster defects is performed and a defect review with a high sampling ratio is

5   performed on the cluster defects if the cluster defects exist.

9.   (original)The method of claim 1 wherein the database is updated according to the result of the defect review after finishing the defect review.

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3